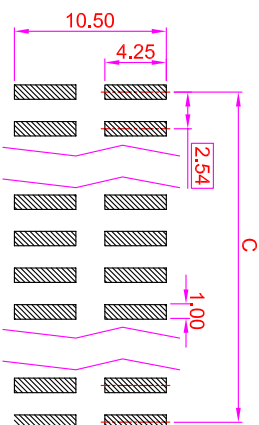
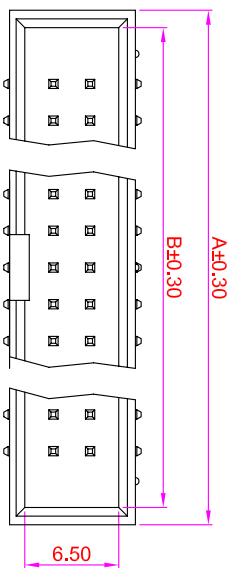
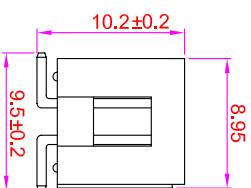
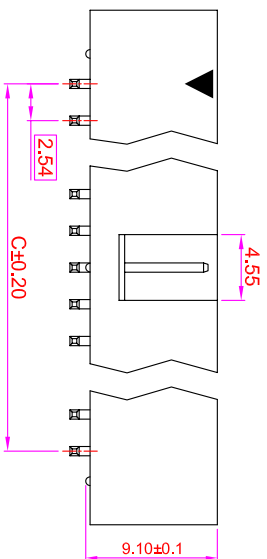


ROHS



Recommended
P.C. Board SMD Layout



CONTACTS	DIMENSION			CONTACTS	DIMENSION		
	A	B	C		A	B	C
06P	15.24	12.94	5.08	24P	38.10	35.70	27.94
08P	17.78	15.48	7.62	26P	40.64	38.24	30.48
10P	20.32	17.92	10.16	30P	45.72	43.32	35.56
12P	22.86	20.56	12.70	34P	50.80	48.40	40.64
14P	25.40	23.10	15.24	40P	58.42	56.02	48.26
16P	27.94	25.54	17.78	44P	63.50	61.20	53.34
20P	33.02	30.62	22.86	50P	71.12	68.72	60.96

Contact Plating Option	Full Gold Plating		Full Tin Plating
	Gold Plated On Contact Area	Tin Plated On Solder Area	
GA : Gold Flash GC : Gold 10u" GD : Gold 15u" GE : Gold 30u"	SA : Gold Flash SC : Gold 10u" SD : Gold 15u" SE : Gold 30u"	TA : Tin 1000u"	

Specifications
 Current Rating : 3 Amps
 Insulator Resistance : 1000 Megohms min.
 Contact Resistance : 20 m ohms max.
 Dielectric Withstanding : AC 600V
 Operating Temperature : -40°C ~ +125°C
 Contact Materil : Brass
 Insulator Material : Polyester, UL 94V-0 Nylon-6T
 Contact Plated : See Option
 Standard:Full Gold Flash

Order Information
 BHA1 - M 0 XX - 0 0 XX - XX

Serial No. _____
 Terminal Type _____
 M : SMD Type _____
 No. of Contacts _____
 Contact Plated _____
 Cap Option _____
 B : Blank (No Cap) _____
 P : Plastic Cap _____
 Packing Method _____
 A : Tray _____
 T : Tube _____
 R : Tape & Reel _____

GENERAL TOLERANCE		單位 (UNIT)	
X. ± 0.50	X. ° ± 5°	mm	
.X ± 0.20	.X ° ± 2°	mm (APPROVAL)	
.XX ± 0.10	.XX ° ± 1°	Alice	
DATE:2008/09/23	SC2	Mary	

製圖 (DRAWING)		製圖 (PART NO.)	
BHA1-M0XX-00XX-XX		BHA1-M0XX-00XX-XX	
Fen-Fen		Fen-Fen	

圖號 (DWG NO.)		比例 (SCALE)	
BHA1-M0XX		Free	
1/1		A	

名稱 (TITLE): **IO PARTS Enterprise Co., Ltd.**
 允允企業有限公司
 Box Header Pitch : 2.54mm
 SMD Type